- 1.(amended) A method of encapsulating a sensitive material comprising:
- (a) plating the sensitive material onto a solid carrier, in an atmosphere inert to the sensitive material, to form a plated material; and
- (b) encapsulating the plated material, wherein encapsulating comprises spraying a melted encapsulant onto the plated material.
  - 2. The method of claim 1 wherein the atmosphere inert to the sensitive material is nitrogen, carbon dioxide, or helium.
  - 3. The method of claim 1 wherein the solid carrier is chilled prior to plating with the sensitive material.
  - 4. The method of claim 3 wherein the solid carrier is chilled by liquid nitrogen.
  - 5. The method of claim 1 wherein the solid carrier is porous or semi porous.
  - 6. The method of claim 5 wherein the solid carrier is maltodextrin, silicon dioxide, starches and starch derivatives, gums, or hydrocolloids.
  - 7. The method of claim 6 wherein the encapsulation occurs in an atmosphere inert to the sensitive material.
  - 8. The method of claim 7 wherein the atmosphere inert to the sensitive material is oxygen-free.
  - 9. The method of claim 7 wherein the atmosphere inert to the sensitive material is nitrogen, carbon dioxide, or helium.
  - 10. The method of claim 1 wherein the sensitive material has a boiling point of between about 40° F. and 250° F.
  - 11. The method of claim 1 wherein the atmosphere inert to the sensitive material is oxygen-free.
  - 12. The method of claim 1 wherein the sensitive material is sprayed onto the solid carrier.
  - 13. The method of claim 1 further comprising encapsulating the plated material with a melted encapsulant.
  - 14. The method of claim 1 wherein the percentage of encapsulant in the resulting encapsulated particles is between about 10 to about 90%.
  - 15. The method of claim 14 wherein the percentage of encapsulant in the resulting encapsulated particles is between about 20 to about 80%.
  - 16. The method of claim 1 wherein the sensitive material is a volatile material.
  - 17. The method of claim 1 wherein the sensitive material is an oxygen sensitive material.
  - 18. The method of claim 1 wherein the sensitive material is a biologically active substance.
- 19. (currently amended) The method of claim 18 wherein the biologically active substance is selected from the group consisting of [Lactobacilli] <u>Lactobacilli</u>, [Bifidobacterium] <u>Bifidobacterium</u>, [Enterococci] <u>Enterococci</u>, phytase, amylases, lipases, invertases, transglutaminases, proteases, lipoxygenases and pentosanases.

20. The method of claim 1 wherein the sensitive material is at least one selected from the group consisting of alcohols, acetones, ketones, aldehydes, organic acids, and antioxidants.

- 21. (amended) A method of encapsulating a sensitive material comprising:
- (a) introducing the sensitive material into an encapsulation vessel, wherein the atmosphere in the encapsulation vessel is inert to the sensitive material; and
- (b) encapsulating the sensitive material, wherein encapsulating comprises spraying a melted encapsulant onto the sensitive material.
- 23. (previously presented) A method according to Claim 21 wherein the sensitive material is lyophilized before being introduced into the encapsulation yessel.
- 23. (previously presented) The method of Claim 21 wherein the atmosphere inert to the sensitive material is nitrogen, carbon dioxide, or helium.
- 24 25. (previously presented) The method of Claim 21 wherein the atmosphere inert to the sensitive material is oxygen-free.
- 26. (previously presented) The method of Claim 21 wherein the percentage of encapsulant in the resulting encapsulated sensitive material is between about 10 to about 90%.
- 27. (previously presented) The method of Claim 26 wherein the percentage of encapsulant in the resulting encapsulated sensitive material is between about 20 to about 80%.
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  8. (previously presented) The method of Claim 21 wherein the sensitive material is a volutile material.
- 28. (previously presented) The method of Claim 21 wherein the sensitive material has a boiling point of between about 40" F and 250" F.

